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May 2014



FQA7N80C_F109

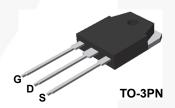
N-Channel QFET $^{\mathbb{R}}$ MOSFET 800 V, 7 A, 1.9 Ω

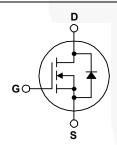
Features

- 7.0 A, 800 V, $R_{DS(on)}$ = 1.9 Ω (Max.) @ V_{GS} = 10 V, I_D = 3.5 A
- Low Gate Charge (Typ. 27nC)
- Low Crss (Typ. 10pF)
- 100% Avalanche Tested
- · RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQA7N80C_F109	Unit	
V _{DSS}	Drain-Source Voltage		800	V	
I _D	Drain Current - Continuous (T _C = 25°C)		7.0	Α	
	- Continuous (T _C = 100°C)		4.4	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	28.0	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy		580	mJ	
I _{AR}	Avalanche Current	(Note 1)	7.0	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	30	mJ	
dv/dt	Peak Diode Recovery dv/dt		4.0	V/ns	
P_D	Power Dissipation (T _C = 25°C)		198	W	
	- Derate above 25°C		1.75	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQA7N80C_F109	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.63	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA7N80C_F109	FQA7N80C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter Test Conditions		Min.	Тур.	Max.	Unit
Off Charac	teristics			I		
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	800			V
$\Delta BV_{DSS}/$ ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		0.93		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 800 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 640 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Charact	teristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3.5 A		1.57	1.9	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.5 A		5.6		S
Dynamic Cl	haracteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	\	1290	1680	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		120	155	pF
C _{rss}	Reverse Transfer Capacitance			10	13	pF
Switching C	Characteristics				1	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 6.6A,		35	80	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		100	210	ns
t _{d(off)}	Turn-Off Delay Time	-		50	110	ns
t _f	Turn-Off Fall Time	(Note 4)		60	130	ns
Qg	Total Gate Charge	$V_{DS} = 640 \text{ V}, I_{D} = 6.6 \text{A},$	/	27	35	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	-/	8.2		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	/-	11		nC
Drain-Source	ce Diode Characteristics and Maximum Ratings	5			7	
I _S	Maximum Continuous Drain-Source Diode Forward Current				7.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				28.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S =7.0 A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 6.6 A,		650		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$		7.0		μС

Notes

 $^{{\}it 1. Repetitive\ rating: pulse-width\ limited\ by\ maximum\ junction\ temperature.}$

^{2.} L = 22.2 mH, I $_{AS}$ = 7 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 $\Omega,$ starting T $_{J}$ = 25 $^{\circ}C.$

 $^{3.}I_{SD} \leq 8.4$ A, di/dt ≤ 200 A/µs, $V_{DD} \leq BV_{DSS},$ starting T_J = $25^{\circ}C.$

^{4.} Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

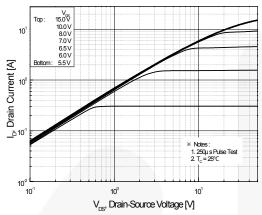


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

Figure 2. Transfer Characteristics

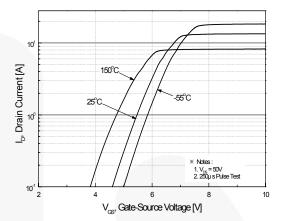


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

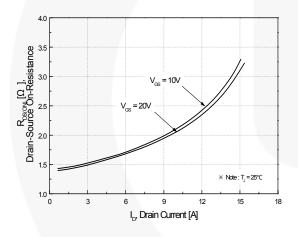


Figure 5. Capacitance Characteristics

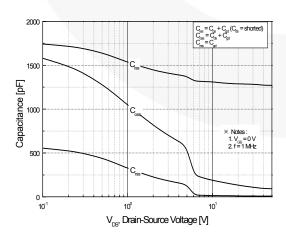
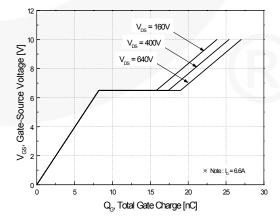


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

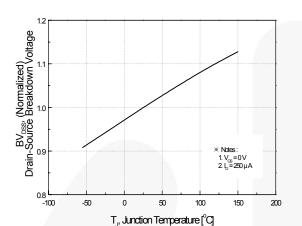


Figure 8. On-Resistance Variation vs. Temperature

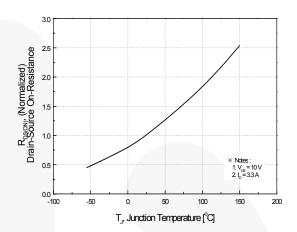
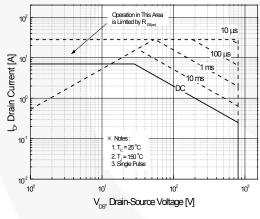


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature



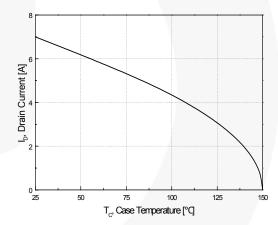
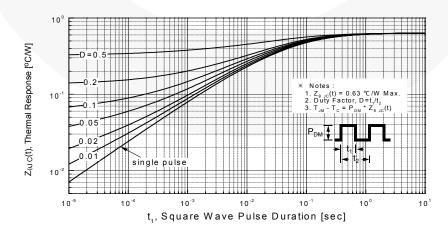


Figure 11. Transient Thermal Response Curve



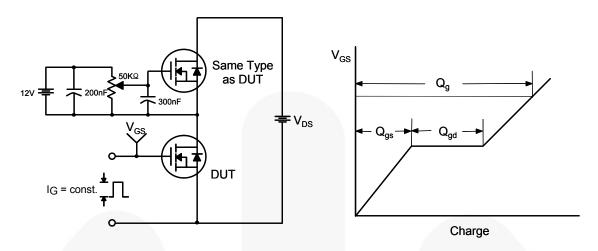


Figure 12. Gate Charge Test Circuit & Waveform

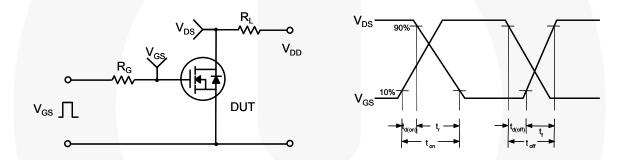


Figure 13. Resistive Switching Test Circuit & Waveforms

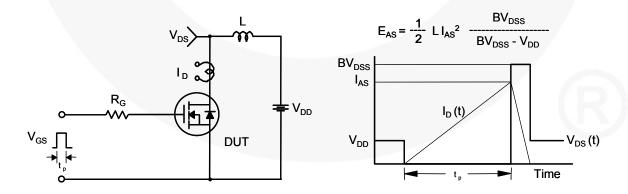


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

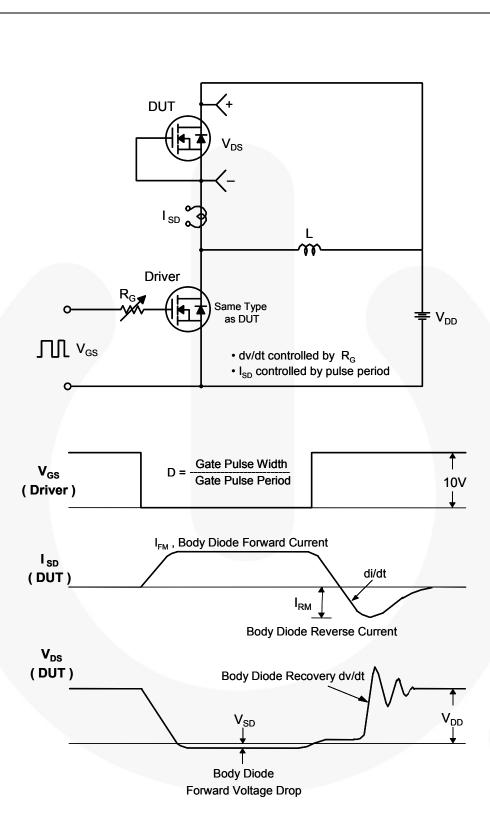
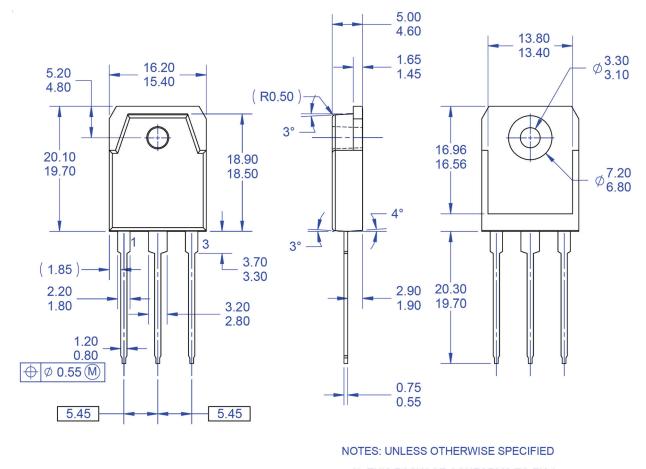
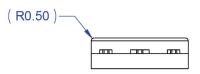


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions





- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
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Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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